



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-11-10
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	I8VY*UR55BZ1	A	0959	2017-11-10
Amount	UoM	Unit type	ST ECOPACK Grade	
263.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	NiPdAuAg	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFP	10-10-1	64	gull wing	
Comment	Package: LQFP 64 LEADS 10X10X1.4 EP UP . MDF valid for CPs: FDA802-VYY and FDA802-VYT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.61	Leadframe	2304
Cobalt	0.002	Die	8

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	18VY*URS5821					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	19.554	mg	supplier	die	Silicon (Si)	7440-21-3		17.765	mg	908510	67548
				supplier	metallization	Copper (Cu)	7440-50-8		1.210	mg	61880	4601
				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	101	8
				supplier	metallization	Platinum (Pt)	7440-06-4		0.075	mg	3836	285
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	51	4
				supplier	metallization	Tungsten (W)	7440-33-7		0.056	mg	2864	213
				supplier	Passivation	Silicon Nitride	12033-89-5		0.048	mg	2455	183
				supplier	Passivation	Silicon Oxide	7631-86-9		0.193	mg	9870	734
				supplier	polymer die coating	Polyimide AH 1200	Proprietary		0.204	mg	10433	776
				supplier	alloy	Copper (Cu)	7440-50-8		97.024	mg	968062	368913
Leadframe	Copper & its alloys	100.225	mg	supplier	alloy	Iron (Fe)	7439-89-6		2.282	mg	22769	8677
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.137	mg	1366	521
				supplier	alloy	Zinc (Zn)	7440-66-6		0.120	mg	1197	456
				supplier	metallization	Nickel (Ni)	7440-02-0		0.606	mg	6046	2304
				supplier	metallization	Palladium (Pd)	7440-05-3		0.020	mg	200	76
				supplier	metallization	Gold (Au)	7440-57-5		0.018	mg	180	68
				supplier	metallization	Silver (Ag)	7440-22-4		0.018	mg	180	68
				supplier	glue	Silver (Ag)	7440-22-4		4.126	mg	895011	15688
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.346	mg	75054	1316
				supplier	glue	Bismaleimide resin	35325-39-4		0.138	mg	29935	522
Bonding wires	Other inorganic materials	2.990	mg	supplier	wire	Copper (Cu)	7440-50-8		2.990	mg	1000000	11369
Encapsulation	Other Organic Materials	135.621	mg	supplier	mold compound	Silica, vitreous	60676-86-0		117.176	mg	863996	445536
				supplier	mold compound	Epoxy Resin	25068-38-6		10.172	mg	75003	38677
				supplier	mold compound	Phenol Resin	29690-82-2		6.781	mg	50000	25783
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.678	mg	4999	2578
				supplier	mold compound	Quartz	14808-60-7		0.407	mg	3001	1548
				supplier	mold compound	Carbon black	1333-86-4		0.407	mg	3001	1548